

描述 / Descriptions

SOT-89 塑封封装 NPN 半导体三极管。Silicon NPN transistor in a SOT-89 Plastic Package.

特征 / Features

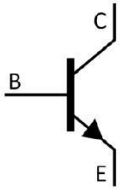
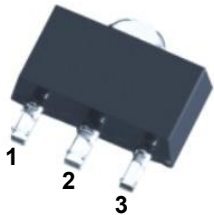
饱和压降低, 极好的 h_{FE} 线性, 与 2SB798 互补。

Low $V_{CE(sat)}$, excellent h_{FE} linearity, complements the 2SB798.

用途 / Applications

用于音频功率放大。

Audio frequency power amplifier applications.

内部等效电路 / Equivalent Circuit**引脚排列 / Pinning**

PIN1 : Base

PIN 2 : Collector

PIN 3 : Emitter

印章代码 / Marking

h_{FE} Classifications Symbol	M	L	K
h_{FE} Range	90~180	135~270	200~400
Marking	HCM **	HCL **	HCK **

极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Collector to Base Voltage	V_{CBO}	30	V
Collector to Emitter Voltage	V_{CEO}	25	V
Emitter to Base Voltage	V_{EBO}	5.0	V
Collector Current-Continuous	I_C	1.0	A
Collector Current -Continuous(Pulse)	I_{CP}	1.5	A
Collector Power Dissipation	P_C	500	mW
Collector Power Dissipation*	$*P_C$	2.0	W
Junction Temperature	T_j	150	°C
Storage Temperature Range	T_{stg}	-55~150	°C

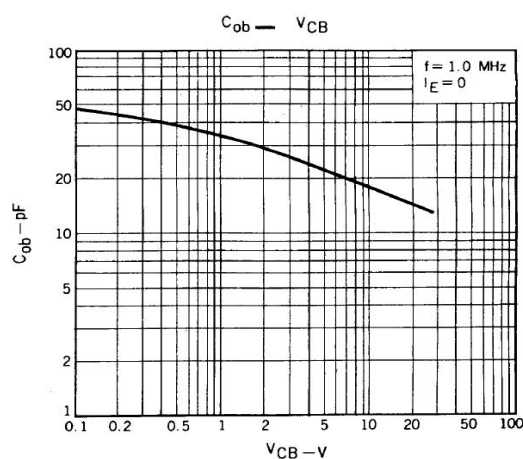
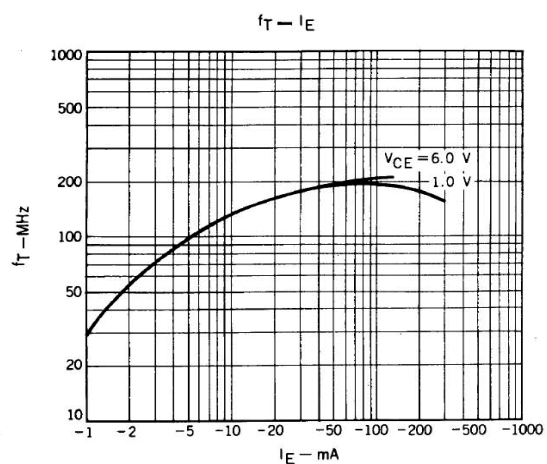
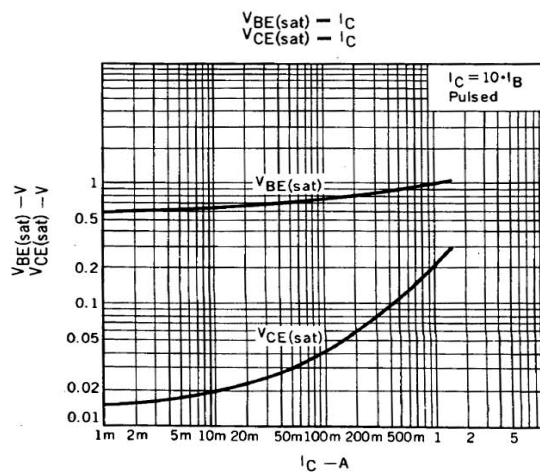
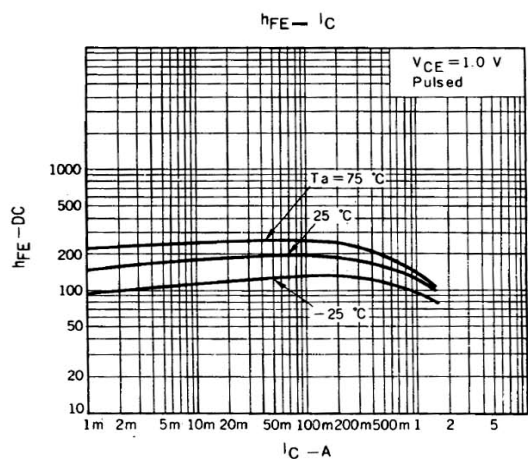
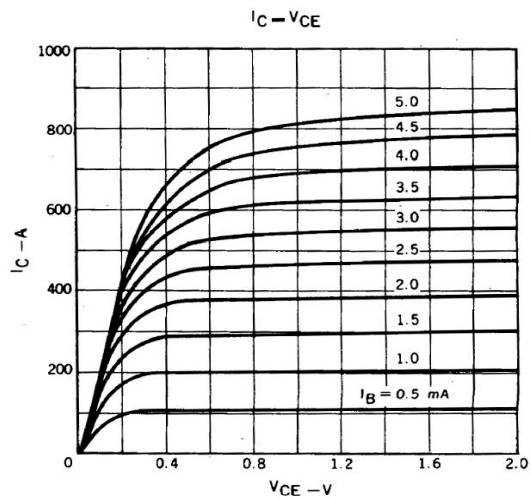
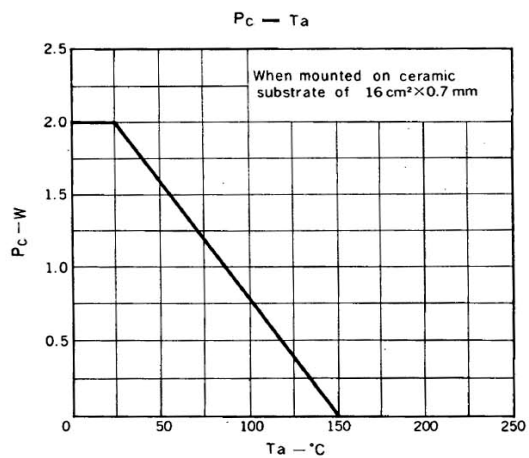
*mounted on ceramic substrate(16cmm²×0.7mm)

*装于 16cmm²×0.7mm 的陶瓷上。

电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Collector Cut-Off Current	I_{CBO}	$V_{CB}=30V$ $I_E=0$			0.1	μA
Emitter Base Cut-Off Current	I_{EBO}	$V_{EB}=5.0V$ $I_C=0$			0.1	μA
DC Current Gain	$h_{FE(1)}$	$V_{CE}=1.0V$ $I_C=100mA$	90	200	400	
	$h_{FE(2)}$	$V_{CE}=1.0V$ $I_C=1.0A$	50	140		
Collector to Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C=1.0A$ $I_B=100mA$		0.21	0.4	V
Base to Emitter Saturation Voltage	$V_{BE(sat)}$	$I_C=1.0A$ $I_B=100mA$		1.0	1.2	V
Base to Emitter Voltage	V_{BE}	$V_{CE}=6.0V$ $I_C=10mA$	600	630	700	mV
Transition Frequency	f_T	$V_{CE}=6.0V$ $I_C=10mA$		130		MHz
Collector Output Capacitance	C_{ob}	$V_{CB}=6.0V$ $I_E=0$ $f=1.0MHz$		22		pF

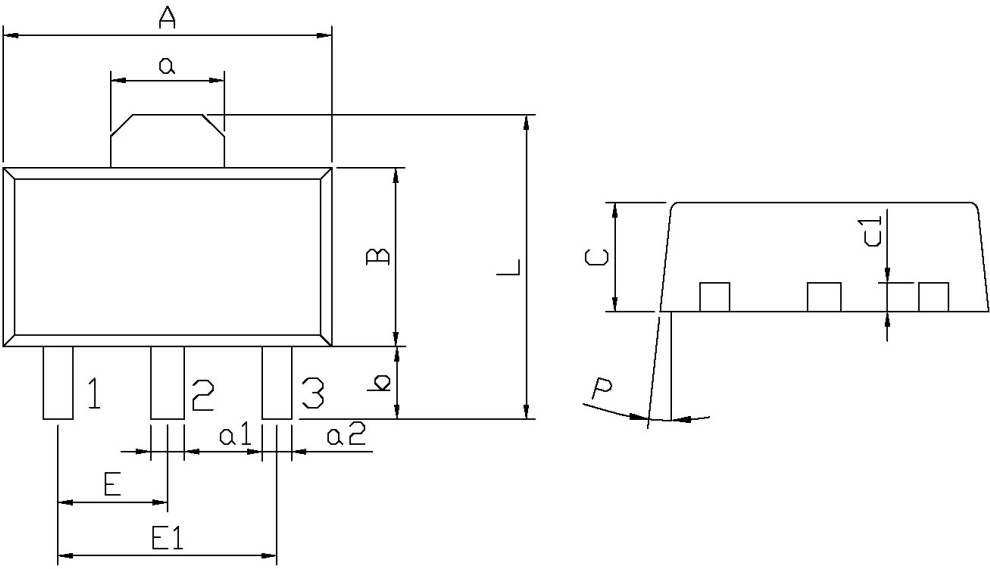
电参数曲线图 / Electrical Characteristic Curve



外形尺寸图 / Package Dimensions

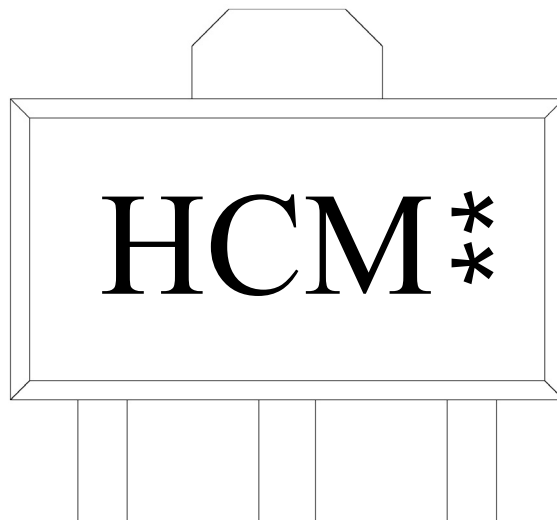
SOT-89

单位: mm



Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
A	4.4	4.7	a1	0.36	0.56
B	2.35	2.65	a2	0.30	0.50
L	3.878	4.478	C	1.40	1.70
a	1.45	1.65	c1	0.35	0.50
E	1.40	1.60	P	6°	
E1	2.80	3.20			
b	0.80	1.20			

印章说明 / Marking Instructions



说明：

H： 为公司代码

C： 为型号代码

M： 为 h_{FE} 分档代码

**： 为生产批号代码，随生产批号变化。

Note:

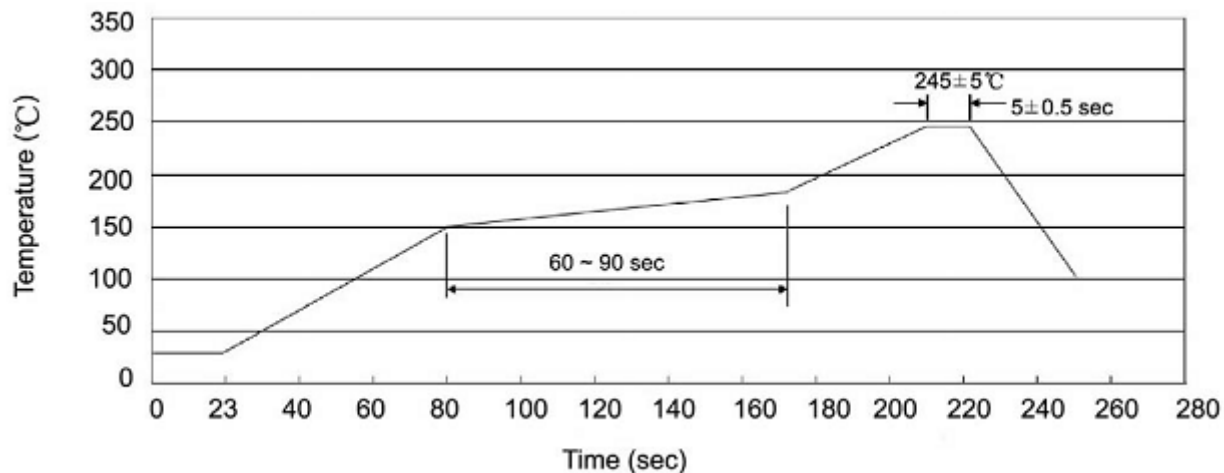
H: Company Code.

C: Product Type.

M: h_{FE} Classifications Symbol

**: Lot No. Code, code change with Lot No.

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 25 ~ 150°C，时间 60 ~ 90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOT-89	1,000	7	7,000	8	56,000	7" ×12	180×120×180	385×257×392

使用说明 / Notices